L Number	Hits	Search Text	DB	Time stamp
1	2505263	semiconductor chip die dice ic (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 21:25
2	252426	(semiconductor chip die dice ic (integrated adj circuit)) with (arranged arranging level multilevel stack stacked stackable stacking)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 21:27
3	28854	((semiconductor chip die dice ic (integrated adj circuit)) with (arranged arranging level multilevel stack stacked stackable stacking)) same (void hole gap air)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 21:28
4	17035	((semiconductor chip die dice ic (integrated adj circuit)) with (arranged arranging level multilevel stack stacked stackable stacking)) with (void hole gap air)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 21:30
5	280	(((semiconductor chip die dice ic (integrated adj circuit)) with (arranged arranging level multilevel stack stacked stackable stacking)) with (void hole gap air)) with spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 22:25
6	280	(((semiconductor chip die dice ic (integrated adj circuit)) with (arranged arranging level multilevel stack stacked stackable stacking)) with (void hole gap air)) with spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 22:26
7	280	(((semiconductor chip die dice ic (integrated adj circuit)) with (arranged arranging level multilevel stack stacked stackable stacking)) with (void hole gap air)) with spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 22:26